

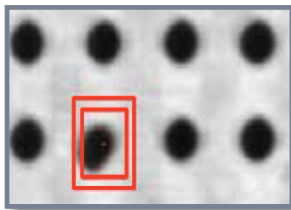
TR7600 SII SERIES



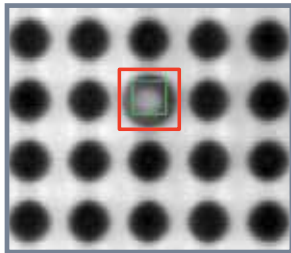
AUTOMATED
X-RAY INSPECTION

TR7600 SII FEATURES

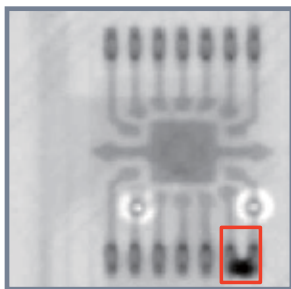
Defect Symptom Images



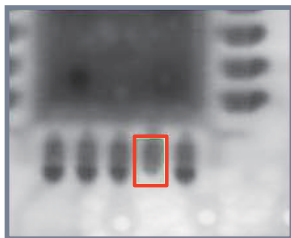
BGA Head-In-Pillow



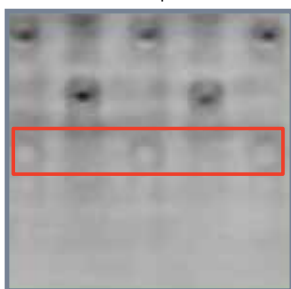
BGA Void



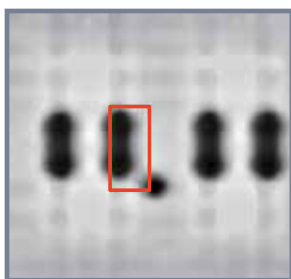
Bridging



QFN Open



Press Fit Pin Defect



Solder Ball

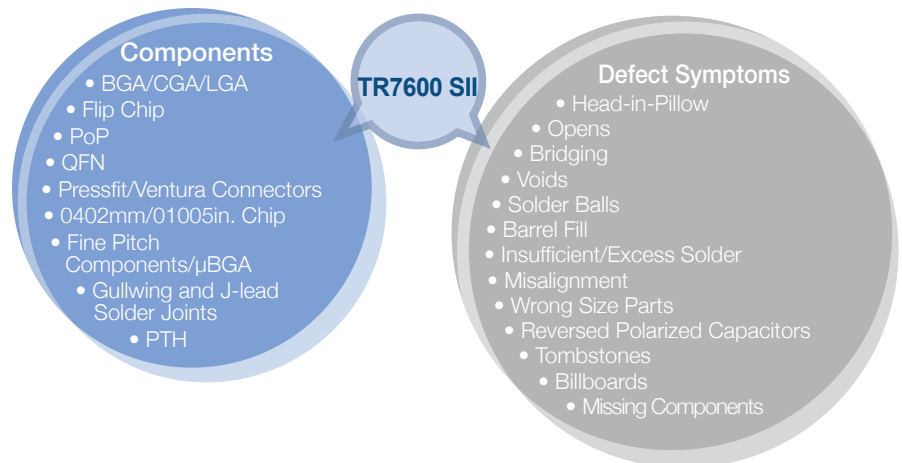
Inline 3D Automated X-ray Inspection

- Fast Inline Automated X-ray Inspection of PCBA
- 2D + 3D Images using multiple angled cameras
- Automated Inspection and Pass/Fail Evaluation
- User selectable X-ray power up to 130 kV/ 300 μ A
- Patented 6-axis motion control for maximum flexibility
- Large board inspection up to 900 x 460 mm

Intelligent Software Solution

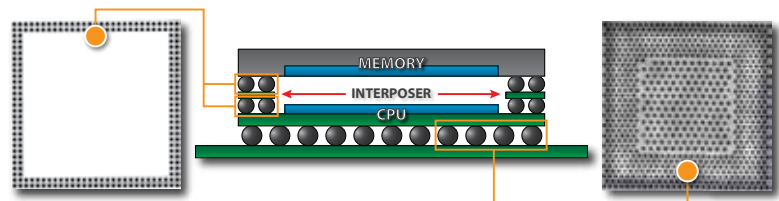
- Automated CAD-based or Manual programming
- Intelligent detection of solder and assembly defects
- Automatic Image quality enhancement for overlapping components and complex defects
- Automatic board warp compensation
- Automated 3D Slice Extraction

Defect Detection Capability



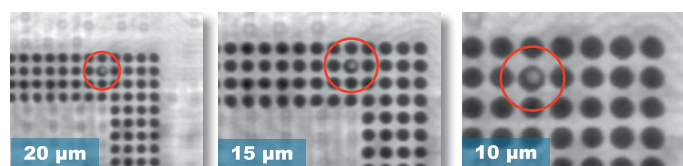
Patented 6-axis Motion Control

TRI's unique motion control system provides clearest images of multi-layer PCBAs and overlapping components, enabling reliable automated inspection of dual-side PCB assemblies without typical shadowing issues.



BlockScan Customized Imaging

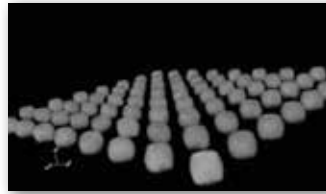
BlockScan module enhances AXI test program coverage by re-scanning selected areas of the tested board using customized system settings. This improves image quality and automated defect detection for most complex PCBAs, including fine pitch μ BGAs, Press Fit and metal shielded components. Using BlockScan, TRI AXI can reliably inspect up to 3-layer PoP packages.



Multiple Resolutions in One Program

CT Inspection Upgrade

Enhanced 3D inspection with planar CT imaging can recreate a complete 3D model of each solder joint, enabling clear analysis of shape irregularities and voiding problems for reliable visual review of borderline solder joints.



Eliminate Board Warp Issues

The TR7600 SII uses multiple laser sensors to accurately measure any PCB assembly deformation and automatically adjusts component inspection parameters to compensate for local board warpage. This ensures reliable inspection of the most complex boards with overlapping and multi-layered components and heavy press-fit connectors.

Accurate Inspection Results

TRI's X-ray systems use intelligent analysis of X-ray data to reliably identify various solder and component defects on a range of components. By automatically separating necessary 3D slices of BGAs, PoPs, PTHs, connectors and angled views of other components, the TR7600 SII can reliably identify defective areas even on the most complex PCB assemblies.

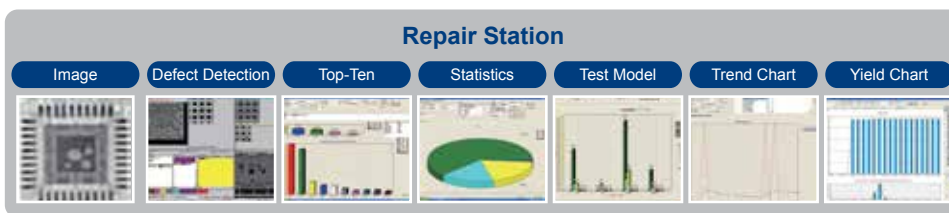
Radiation Safe Design

Designed with safety in mind, TRI's AXI systems have full lead shielding which prevents harmful exposure in everyday use and reduces X-ray leakage below background radiation levels of 0.5 μ Sv/hr.

The certified safety design conforms to USFDA Code of Federal Regulations Title 21, Part 1020.40.

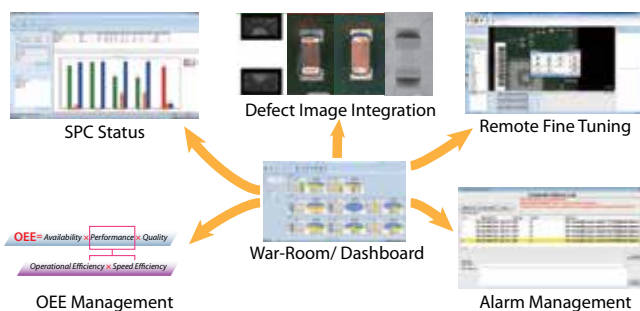
Repair Station

The TR7600 SII collects a wide range of inspection data to offer instantaneous process monitoring and analysis. This integrated approach offers clear statistical feedback that improves defect management and enhances the efficiency of the inspection process.

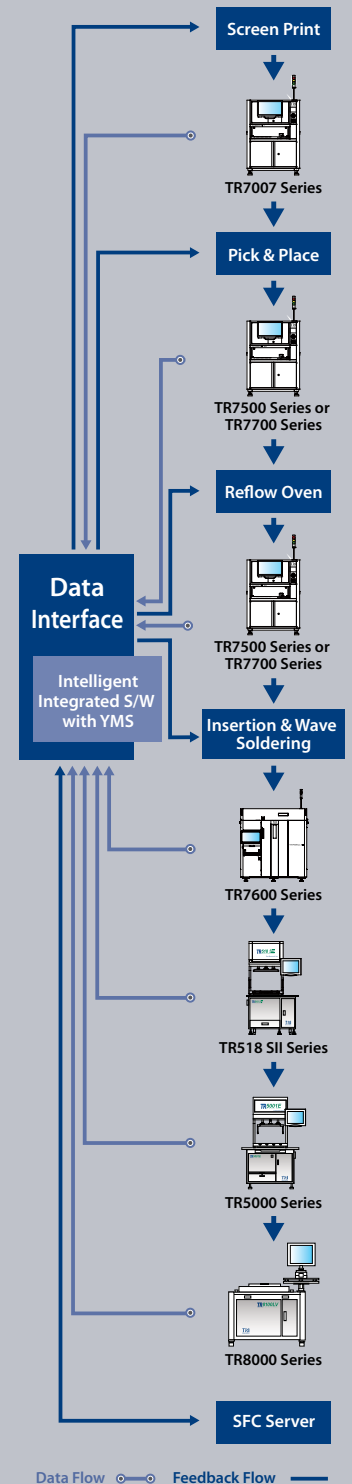


Yield Management System 4.0

YMS 4.0 provides real-time inspection status across SPI, AOI and AXI systems and monitors SPC and Alarm status, and supports remote fine-tune throughout the SMT line. The centralized inspection management provides top 5 to 10 defects and defective images, OEE review and management, issue and root cause drill down line by line, by station and by process, which improves quality and productivity analysis. YMS 4.0 supports Industry 4.0 initiative.



Yield Management System*



- Inspection results and data integration
- Real time SPC and production yield management
- Quality reports and close loop tracking
- Support defect component analysis and improvements
- Knowledge Management (KM)
- Productivity and Quality Management

* Optional

X-Ray & Imaging System



X-ray Source	130 KV max (user adjustable)
Image Resolutions	10 μ m, 15 μ m, 20 μ m (factory setting)
Camera	High-performance, ultra-sensitive line-scan cameras

Inspection Functions

Component Level Defects	Missing, Misalignment, Tombstoning, Billboarding, Tantalum Polarity, Rotation
Joint Level Defects	Insufficient Solder, Excess Solder, Bridging, Open, Solder Ball, Non-wetting, Void, Lifted Lead

X-Y Table & Control

High-precision ball screw/servo motor with DSP-based motion controller

X-Y Axis Resolution	1 μ m
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PCB & Conveyor System

Min. PCB Size	50 x 50 mm (1.97 x 1.97 in.)
Max. PCB Size	900 x 460 mm (35.4 x 18.1 in.)
PCB Thickness	0.6 - 5 mm
Max. PCB Weight	3 kg (7 lbs) [8 kg (18 lbs) optional]
PCB Carrier/Fixing	Motor Driven/Clamping
Clearance	
Top 20 μ m	50 mm (1.97 in.)
15 μ m	30 mm (1.18 in.)
10 μ m	15 mm (0.59 in.)
Bottom	40 mm (1.57 in.)
Edge	3 mm (0.11 in.)

Dimensions

Dimensions	(W) 1500 mm x (D) 2060 mm x (H) 1650 mm (Does not include signal tower, signal tower height: 515 mm [20.3 in.]) (W) 59.1 in. x (D) 81.1 in. x (H) 65.0 in.
Weight	3250 kg (7165 lbs)
Power Requirement	200 - 240 V Single phase, 50/60Hz 4 kVA
Air Requirement	72 psi - 87 psi (5 - 6 Bar)

Optional Accessories

Barcode Scanner, Repair Station, Offline Editor & Yield Management System (YMS 4.0), YMS Lite, 3D CT Upgrade Kit

U.S., Taiwan, China and Japan Patented: System and Method for Laminography Inspection

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TRI 德律 TRI INNOVATION

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Headquarters

7F., No.45, Dexing West Rd.,
Shilin Dist., Taipei City
11158, Taiwan
TEL: +886-2-2832-8918
FAX: +886-2-2831-0567
E-Mail: sales@tri.com.tw
http://www.tri.com.tw

Linkou, Taiwan

No.256, Huaya 2nd Rd.,
Guishan Dist., Taoyuan
City 33383, Taiwan
TEL: +886-2-2832-8918
FAX: +886-3-328-6579

Hsinchu, Taiwan

7F., No.47, Guangming 6th
Rd., Zhubei City, Hsinchu
County 30268, Taiwan
TEL: +886-2-2832-8918
FAX: +886-3-553-9786

Shenzhen, China

5F.3, Guangxia Rd.,
Shang-mei-lin Area,
Fu-Tian Dist., Shenzhen,
Guangdong, 518049, China
TEL: +86-755-83112668
FAX: +86-755-83108177
E-mail: shenzhen@cn.tri.com.tw

Suzhou, China

B Unit, Building 4, 78 Xinglin St.,
Suzhou Industrial Park, 215123,
China
TEL: +86-512-68250001
FAX: +86-512-68096639
E-mail: suzhou@cn.tri.com.tw

Shanghai, China

Room 6C, Building 14, Aly. 470,
Guiping Rd., Xuhui Dist.,
Shanghai, 200233, China
TEL: +86-21-54270101
FAX: +86-21-64957923
E-mail: shanghai@cn.tri.com.tw

USA

1923 Hartog Drive
San Jose, CA 95131 U.S.A
TEL: +1-408-567-9898
FAX: +1-408-567-9288
E-mail: triusa@tri.com.tw

Europe

O'Brien Strasse 14
91126 Schwabach
Germany
TEL: +49-9122-631-2127
FAX: +49-9122-631-2147
E-mail: trieuropa@tri.com.tw

Japan

2-9-9 Midori, Sumida-ku,
Tokyo, 130-0021 Japan
TEL: +81-3-6273-0518
FAX: +81-3-6273-0519
E-mail: trijp@tri.com.tw

Korea

No.207 Daewoo-Technopia,
768-1 Wonsi-Dong, Danwon-Gu,
Ansan City, Gyeonggi-Do, Korea
TEL: +82-31-470-8858
FAX: +82-31-470-8859
E-mail: trikr@tri.com.tw

Malaysia

C11-1, Ground Floor, Lorong
Bayan Indah 3 Bay Avenue,
11900 Bayan Lepas Penang,
Malaysia
TEL: +604-6461171
E-mail: trimy@tri.com.tw